Description

The SX8H10S uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 100V I_D =8.3A

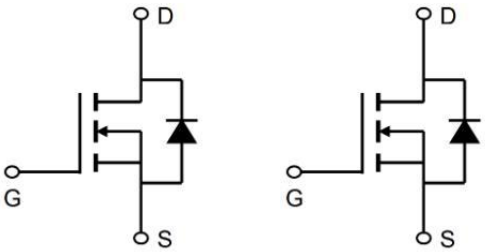
$R_{DS(ON)}$ < 120mΩ @ V_{GS}=10V

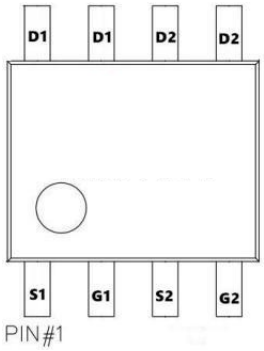
Application

Lithium battery protection

Wireless impact

Mobile phone fast charging





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Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	100	V
VGS	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Drain Current, V_{GS} @ 10V	8.3	A
I_D@T_C=100℃	Drain Current, V_{GS} @ 10V	6.5	A
IDM	Pulsed Drain Current[1]	24.3	A
P_D@T_C=25℃	Total Power Dissipation	1.5	W
EAS	Single Pulse Avalanche Energy[4]	6.1	mJ
TSTG	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃
RθJA	Maximum Thermal Resistance, Junctionambient	85	℃/W
RθJC	Maximum Thermal Resistance, Junction-case	8.1	℃/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250μA	100	107	-	V
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	VDS=0V, VGS=±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1.0	1.6	2.5	V
RDS(on)	Static Drain-Source on-Resistance note3	VGS=10V, ID=10A	-	100	120	mΩ
		VGS=4.5V, ID=8A	-	115	135	mΩ
Ciss	Input Capacitance	VDS=25V, VGS=0V, f=1.0MHz	-	610	-	pF
Coss	Output Capacitance		-	40	-	pF
Crss	Reverse Transfer Capacitance		-	25	-	pF
Qg	Total Gate Charge	VDS=30V, ID=10A, VGS=10V	-	12	-	nC
Qgs	Gate-Source Charge		-	2.2	-	nC
Qgd	Gate-Drain("Miller") Charge		-	2.5	-	nC
td(on)	Turn-on Delay Time	VDS=30V, ID=5A, RG=1.8Ω, VGS=10V	-	7	-	ns
tr	Turn-on Rise Time		-	5	-	ns
td(off)	Turn-off Delay Time		-	16	-	ns
tf	Turn-off Fall Time		-	6	-	ns
IS	Continuous Source Current1,5	VG=VD=0V , Force Current	-	-	10	A
ISM	Pulsed Source Current2,5		-	-	40	A
VSD	Diode Forward Voltage2	VGS=0V, IS=10A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	IF=10A, dI/dt=100A/μs	-	21	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	21	-	nC

Notes:

1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.

2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3、The EAS data shows Max. rating . The test condition is VDD =80V,VGS =10V,L=0.1mH,IAS =3A

4、The power dissipation is limited by 150℃junction temperature

5、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation

Typical Characteristics

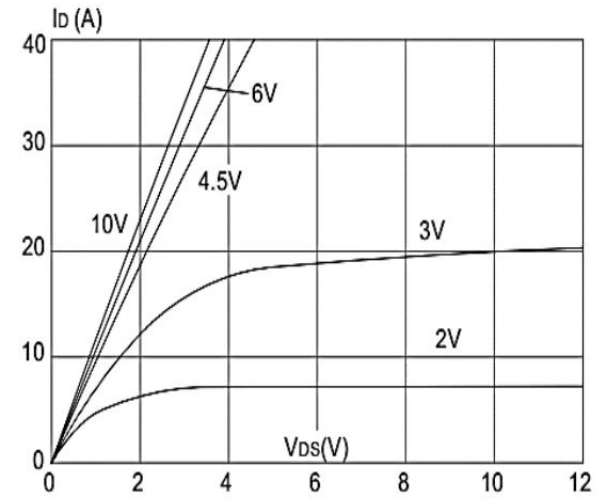


Figure1: Output Characteristics

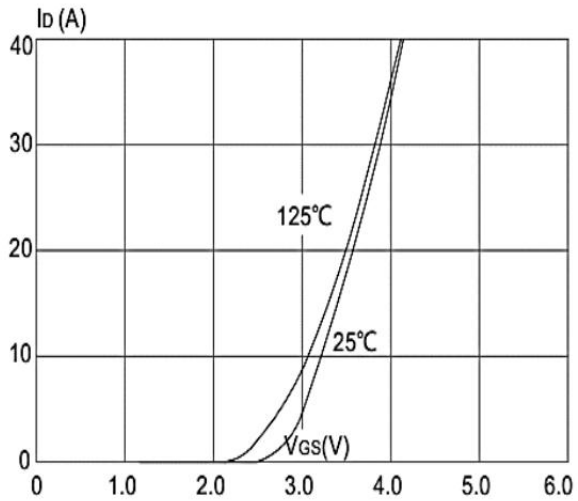


Figure 2: Typical Transfer Characteristics

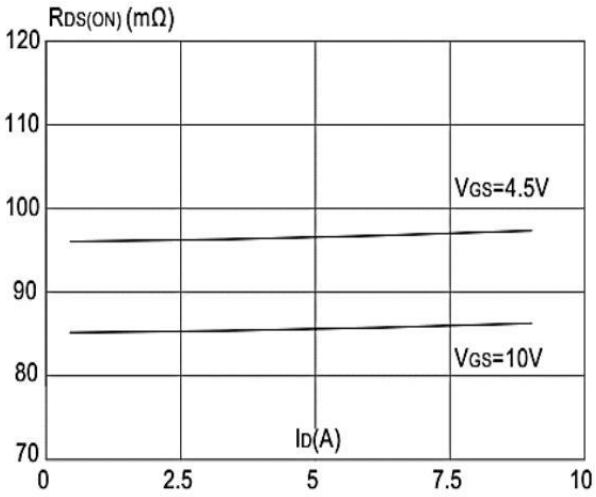


Figure 3:On-resistance vs. Drain Current

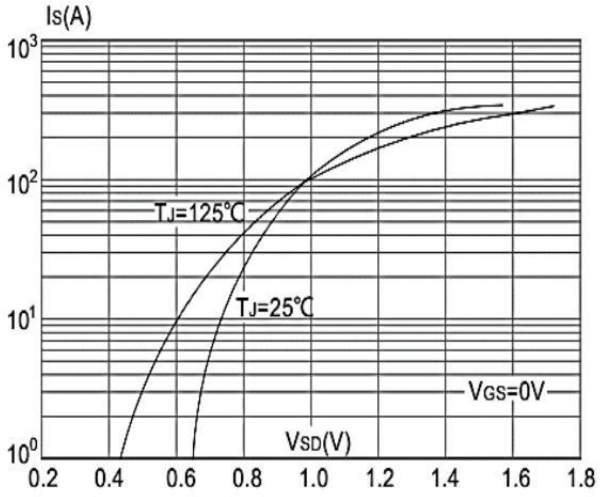


Figure 4: Body Diode Characteristics

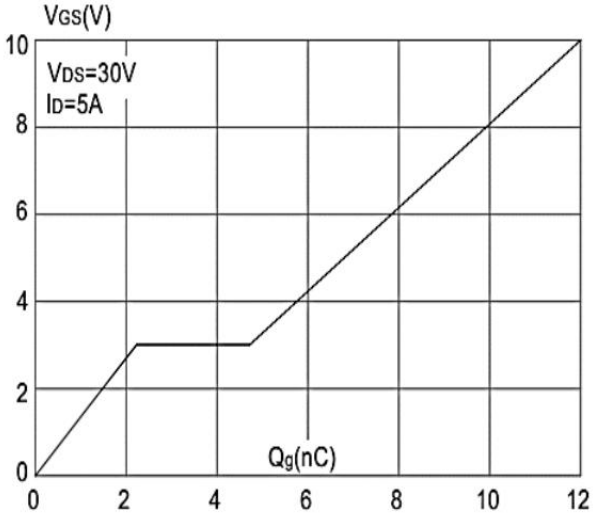


Figure 5: Gate Charge Characteristics

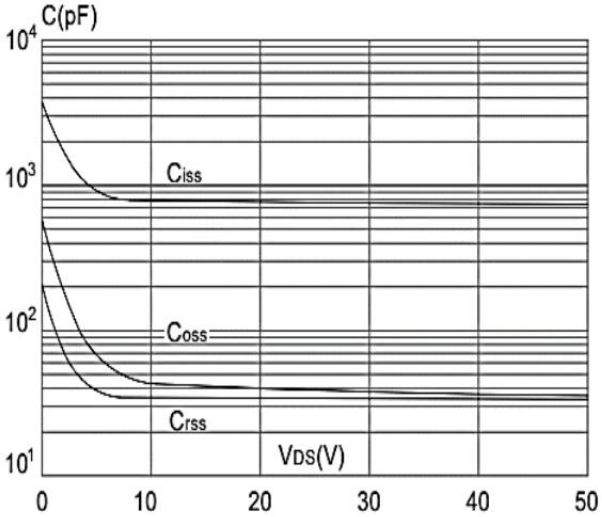


Figure 6: Capacitance Characteristics

Typical Characteristics

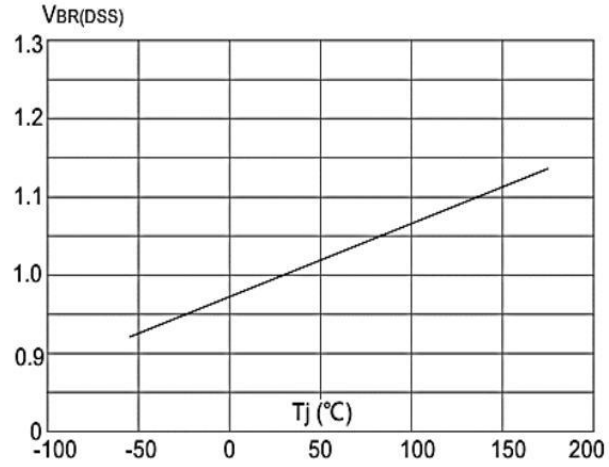


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

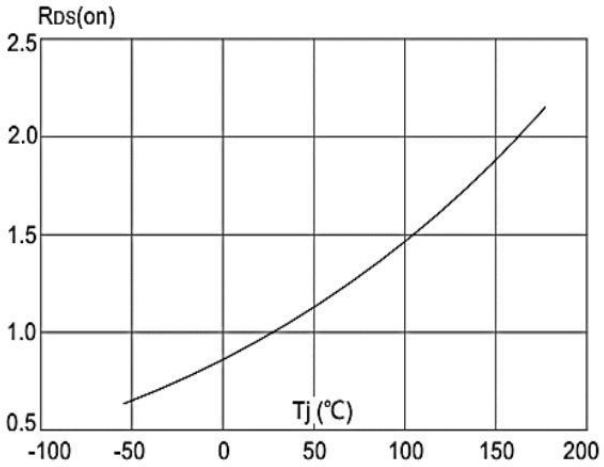


Figure 8: Normalized on Resistance vs. Junction Temperature

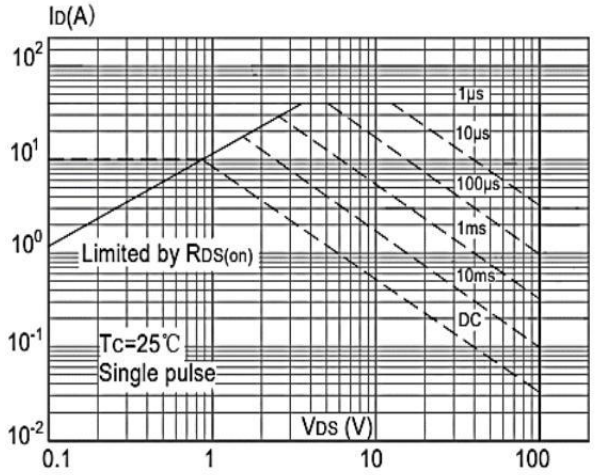


Figure 9: Maximum Safe Operating Area

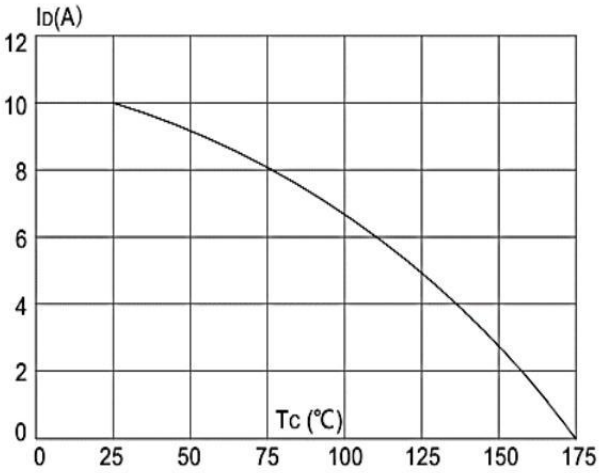


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

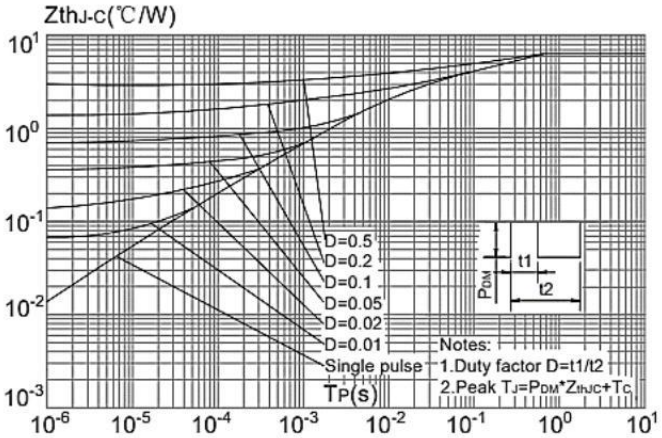
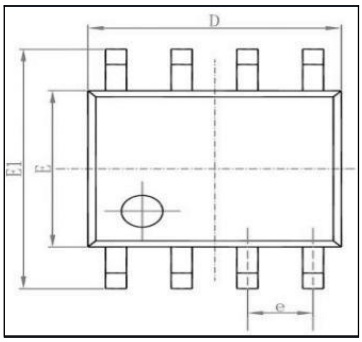
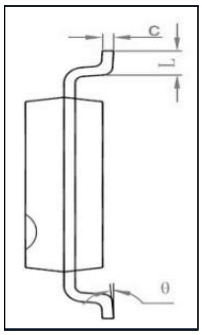
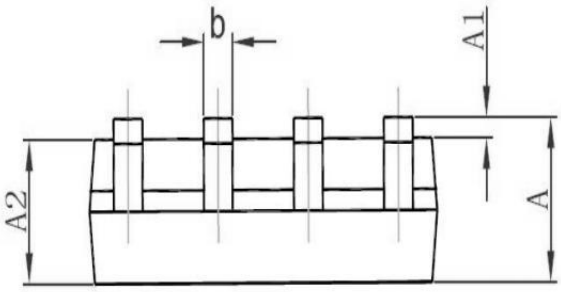


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien

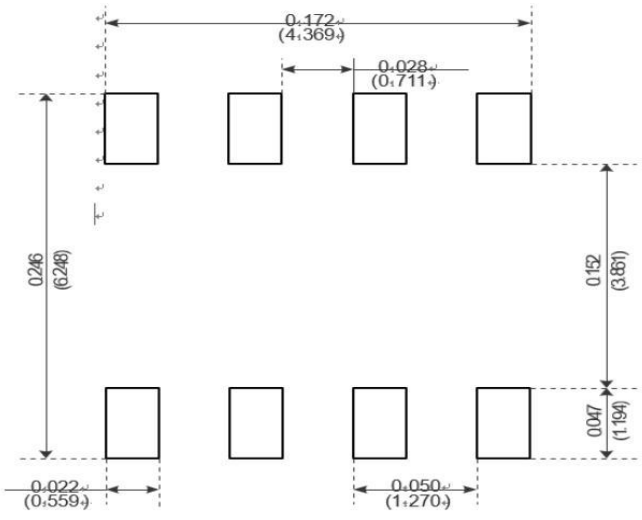
Package Mechanical Data-SOP-8







Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOP-8L		3000